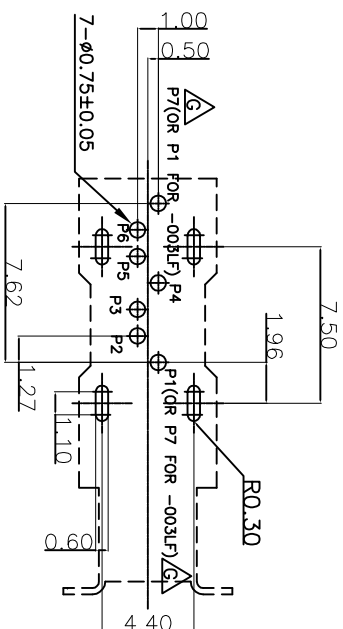
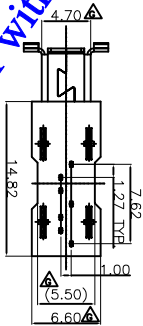
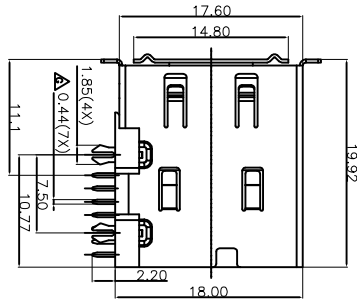
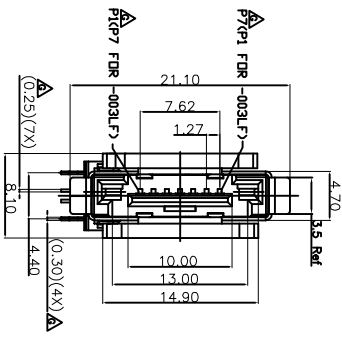
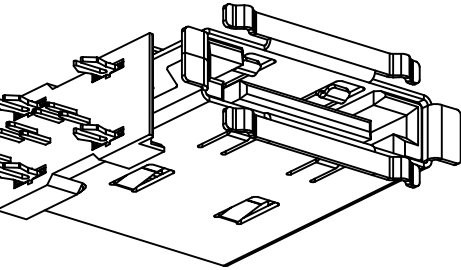


PRODUCT NO.
10074141-001LF
10074141-003LF



RECOMMEND P.C.B. BOARD LAYOUT
PCB TOLERANCE:±0.05



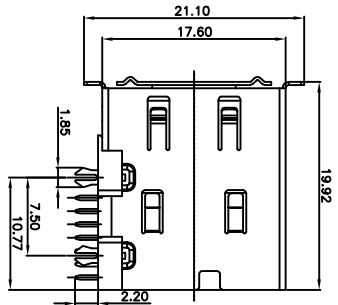
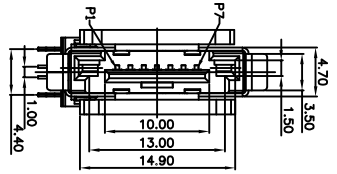
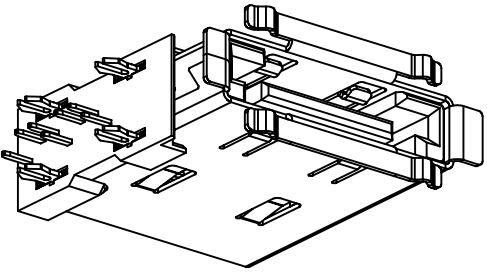
PIN DEFINITION

| ESATA | NAME | TYPE |
|-------|------|------|
| P1 | GND | GND |
| P2 | A+ | A+ |
| P3 | A- | A- |
| P4 | GND | GND |
| P5 | B- | B- |
| P6 | B+ | B+ |
| P7 | GND | GND |

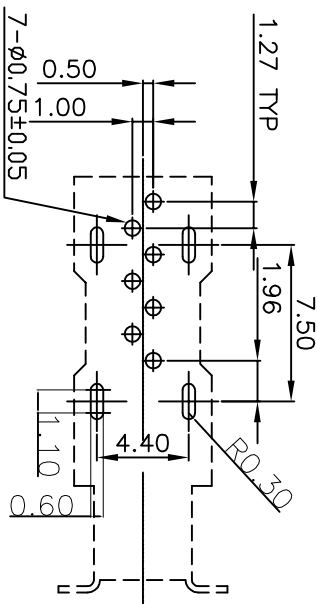
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- NOTES:
1. MATERIAL: HOUSING:THERMALPLASTIC HIGH TEMP WITH 30% G/F US94 V-0
 2. FINISH: 500" MIN. MATT TIN PLATING ON SOLDERABLES
 3. THE HOUSING WILL WITHSTAND TO 280C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB
 4. PRODUCT SPEC : GS-12-386
 5. PACKING SPEC : GS-14-1109
 6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- PACKING: TRAY PACKING
BLANK: TRAY PACKING
1. 150" GOLD PLATING
2. 0.7" GOLD PLATING
3. 150" GOLD PLATING WITH NEW PINOUT ASSIGNMENT

| mat'l. code | surface | sg | tolerance | projection | product family | | | | | | | | |
|-------------|------------|----------|-----------------|--------------|--------------------------------------|--------|--------|--------|--------|--------|--------|--------|-----|
| 14 | ISO 1302 | ∇ | ISO 406 ISO 100 | 100 | 533 | | | | | | | | |
| ltr | ecn no | dr | date | ISO 1302 | tolerance unless otherwise specified | | | | | | | | |
| A | 107-1074 | SLIN | 2007-05-23 | angle | .X±0.38 | | | | | | | | |
| B | 108-1082 | SLIN | 2008-04-28 | linear | .XX±0.25 | | | | | | | | |
| C | 110-0184 | SLIN | 2010-12-14 | linear | .XXX±0.100 | | | | | | | | |
| D | T-00544 | SLIN | 2011-08-31 | STERLING LIN | 2007-05-21 | | | | | | | | |
| E | 2011-10-17 | eng | 2011-10-17 | HKLIM | 2016-03-03 | | | | | | | | |
| F | 2012-06-08 | chr | 2012-06-08 | HKLIM | 2016-03-03 | | | | | | | | |
| G | 2016-03-03 | ppr | 2016-03-03 | KPTAY | 2016-03-03 | | | | | | | | |
| Sheet | revision | G | G | 107109 | 111113 | 115117 | 119121 | 123125 | 127129 | 131133 | 135137 | 139 | |
| index | sheet | 1 | 2 | 3 | 106108 | 110112 | 114116 | 118120 | 122124 | 126128 | 130132 | 134136 | 138 |



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P.C.B.OARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

PIN DEFINITION

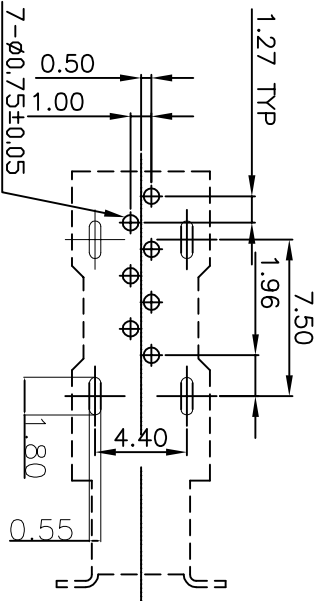
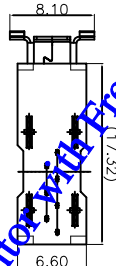
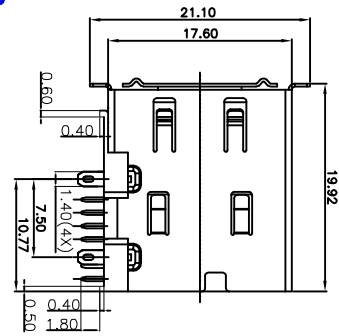
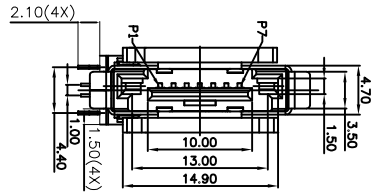
| ESATA | NAME | TYPE |
|-------|------|------|
| P1 | GND | A+ |
| P2 | A+ | A- |
| P3 | A- | GND |
| P4 | GND | B- |
| P5 | B- | B+ |
| P6 | B+ | GND |
| P7 | GND | |

| mat'l. code | 14 | surface | sg | tolerance | projection | product family | | | | | | | | | | | | | | | |
|-------------|------------|---------|------------|---------------------------------------|------------|-----------------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| lfr | ecm no | dr | date | ISO 1302 | ISO 406 | ISO 100 | | | | | | | | | | | | | | | |
| A | 107-1074S | LIN | 2007-05-23 | tolerances unless otherwise specified | MM | 533 | | | | | | | | | | | | | | | |
| B | 108-1082S | LIN | 2008-04-28 | angle | MM | E-SATA_UP_RIGHT | | | | | | | | | | | | | | | |
| C | 110-0184S | LIN | 2010-12-14 | line ar | MM | DIP_TYPE | | | | | | | | | | | | | | | |
| D | T-00544QS | LIN | 2011-08-31 | σ±Z | SCALE 2:1 | | | | | | | | | | | | | | | | |
| E | EX-S-01187 | HKL | 2011-10-17 | STERLING | LIN | 2007-05-21 | | | | | | | | | | | | | | | |
| F | EX-S-01187 | HKL | 2012-06-08 | HKLIM | 2016-03-03 | | | | | | | | | | | | | | | | |
| G | EX-S-2340 | HKL | 2016-03-03 | KPTAY | 2016-03-03 | | | | | | | | | | | | | | | | |
| Sheet | Revision | G | G | 107 | 109 | 111 | 113 | 115 | 117 | 119 | 121 | 123 | 125 | 127 | 129 | 131 | 133 | 135 | 137 | 139 | |
| Index | Sheet | 1 | 2 | 3 | 106 | 108 | 110 | 112 | 114 | 116 | 118 | 120 | 122 | 124 | 126 | 128 | 130 | 132 | 134 | 136 | 138 |

- NOTES:
1. MATERIAL: HOUSING: THERMAL PLASTIC HIGH TEMP WITH 30% G/F U94 V-0 COLOR: BLACK CONTACT: COPPER ALLOY SHELL/BOARD LOCK: COPPER ALLOY
 2. CONTACT: GOLD PLATING ON CONTACT AREA 100µ" MIN. WATT TIN PLATING ON SOLDERMILLS 50µ" MIN. NICKEL UNDERPLATING OVER ALL BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL SHELL/BOARD LOCK: 50µ" MIN. WATT TIN PLATING OVER ALL
 3. N/A WAVE SOLDER APPLICATION WITH A 1.5MM P/B
 4. PRODUCT SPEC : GS-12-398
 5. PACKING SPEC : GS-14-1109
 6. PRODUCT NUMBERING: 10074141 - 0 0 0 LF LEAD FREE
- PAKING: BLANK: TRAY PACKING
1: 1.5µ" GOLD PLATING
2: 5/7" GOLD PLATING
6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- 1: LAYOUT/2



dwg no 10074141 sheet 2 of 3 size A3



P.C.B. BOARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

| PIN DEFINITION | |
|----------------|-----------|
| ESATA | NAME TYPE |
| | P1 GND |
| | P2 A+ |
| | P3 A- |
| | P4 GND |
| | P5 B- |
| | P6 B+ |
| | P7 GND |

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| mat'l. code | 14 | surface | ISO 1302 | ISO 406 | ISO 150 | 100 | projection | product family | 533 | | | | | | | | | | | | |
|-------------|------------|---------|------------|---------------------------------------|---------|--------------|------------|-----------------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| lfr | ecn no | dr | date | tolerances unless otherwise specified | angles | line ar | .XXX±0.25 | MM | | | | | | | | | | | | | |
| A | 107-1074S | LIN | 2007-05-23 | | | | | E-SATA_UP_RIGHT | | | | | | | | | | | | | |
| B | 108-1082S | LIN | 2008-04-28 | | | | | DIP_TYPE | | | | | | | | | | | | | |
| C | 110-0184S | LIN | 2010-12-14 | 0±Z | | .XXX±0.100 | scale 2:1 | | | | | | | | | | | | | | |
| D | T-00544QS | LIN | 2011-08-31 | dr | | STERLING LIN | 2007-05-24 | | | | | | | | | | | | | | |
| E | EX-S-0078R | HKL | 2011-10-17 | engr | | HKLIM | 2016-03-03 | | | | | | | | | | | | | | |
| F | EX-S-0118R | HKL | 2012-06-08 | chr | | HKLIM | 2016-03-03 | | | | | | | | | | | | | | |
| G | EX-S-234W | HKL | 2016-03-03 | dpd | | KPTAY | 2016-03-03 | | | | | | | | | | | | | | |
| Sheet | Revision | 1 | 2 | 3 | 107 | 109 | 111 | 113 | 115 | 117 | 119 | 121 | 123 | 125 | 127 | 129 | 131 | 133 | 135 | 137 | 139 |
| Index | Sheet | G | G | G | 106 | 108 | 110 | 112 | 114 | 116 | 118 | 120 | 122 | 124 | 126 | 128 | 130 | 132 | 134 | 136 | 138 |

- NOTES:
1. MATERIAL: THERMOPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0 ROUSING: COLOR:BLACK
 2. FINISH: CONTACT: COPPER ALLOY SHELL/BOARD LOCK: COPPER ALLOY
 3. CONTRACT: GOLD PLATING ON CONTACT AREA
 4. BOARD LOCK: 50μ" MIN. NICKEL UNDERPLATING OVER ALL SHELL/BOARD LOCK: 50μ" MIN. NICKEL PLATING OVER ALL
 5. IN A WAVE SOLDER APPLICATION WITH A 1.5MM PCB
 6. PRODUCT SPEC: 05-12-386
 7. PACKING SPEC: 05-14-1109
 8. PRODUCT NUMBERING: 10074141 - 2 0 X X X LF — LEAD FREE
6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- 1: 15μ" GOLD PLATING
 - 2: 0.7μ" GOLD PLATING
 - 2: LAYOUTS
 - PACKING: TRAY PACKING
 - BLANK: TRAY PACKING